SLLS100A - JUNE 1984 - REVISED MAY 1995

- Bidirectional Transceiver
- Meets or Exceeds the Requirements of ANSI Standards EIA/TIA-422-B and ITU Recommendation V.11
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- 3-State Driver and Receiver Outputs
- Individual Driver and Receiver Enables
- Wide Positive and Negative Input/Output Bus Voltage Ranges
- Driver Output Capability . . . ±60 mA Max
- Thermal-Shutdown Protection
- Driver Positive- and Negative-Current Limiting
- Receiver Input Impedance . . . 12 k Ω Min
- Receiver Input Sensitivity . . . ±200 mV
- Receiver Input Hysteresis . . . 50 mV Typ
- Operates From Single 5-V Supply
- Low Power Requirements

description

The SN75176A differential bus transceiver is a monolithic integrated circuit designed for bidirectional data communication on multipoint bus-transmission lines. It is designed for balanced transmission lines and meets ANSI Standard EIA/TIA-422-B and ITU Recommendation V.11.

The SN75176A combines a 3-state differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, that can be externally connected together to function as a direction control. The driver differential outputs and the receiver differential inputs are connected internally to form differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus whenever the driver is disabled or $V_{CC} = 0$. These ports feature wide positive and negative common-mode voltage ranges making the device suitable for party-line applications.

The driver is designed to handle loads up to 60 mA of sink or source current. The driver features positive- and negative-current limiting and thermal shutdown for protection from line fault conditions. Thermal shutdown is designed to occur at a junction temperature of approximately 150°C. The receiver features a minimum input impedance of 12 k Ω , an input sensitivity of ± 200 mV, and a typical input hysteresis of 50 mV.

The SN75176A can be used in transmission-line applications employing the SN75172 and SN75174 quadruple differential line drivers and SN75173 and SN75175 quadruple differential line receivers.

The SN75176A is characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



Function Tables

DRIVER

INPUT	ENABLE	OUTI	PUTS
D	Α	В	
Н	Н	Н	L
L	Н	L	Н
Х	L	z	Z

RECEIVER

DIFFERENTIAL INPUTS A – B	ENABLE RE	OUTPUT R
V _{ID} ≥ 0.2 V	L	Н
$-0.2 \text{ V} < \text{V}_{1D} < 0.2 \text{ V}$	L	?
$V_{ID} \le -0.2 V$	L	L
X	Н	Z
Open	L	?

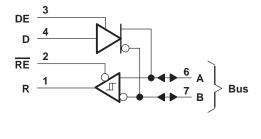
H = high level, L = low level, ? = indeterminate,

logic symbol†

EN1 EN2 1♡ 1♡ ┰

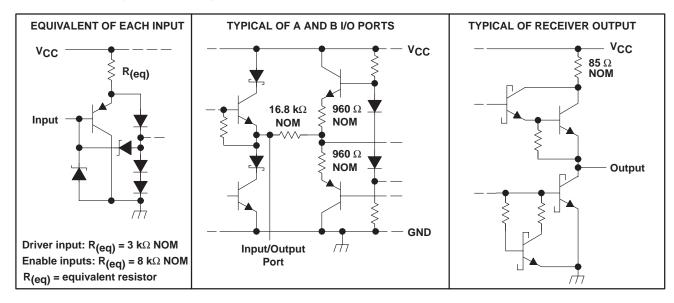
 $\ensuremath{^{\dagger}}$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



X = irrelevant, Z = high impedance (off)

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	
Voltage range at any bus terminal	10 V to 15 V
Enable input voltage, V _I	5.5 V
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stg}	– 65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential input/output bus voltage, are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 105°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW	261 mW
Р	1100 mW	8.8 mW/°C	704 mW	396 mW

SN75176A DIFFERENTIAL BUS TRANSCEIVER

SLLS100A - JUNE 1984 - REVISED MAY 1995

recommended operating conditions

			MIN	TYP	MAX	UNIT
Supply voltage, V _{CC}			4.75	5	5.25	V
Voltage at any bus terminal (sepa	rately or common mode), V _I or V _{IC}		-7		12	V
High-level input voltage, VIH	D, DE, and RE		2			V
Low-level input voltage, V _{IL}	D, DE, and RE				0.8	V
Differential input voltage, V _{ID} (see	Note 2)		±12		V	
High level output gurrent leve	Driver				-60	mA
High-level output current, IOH	Receiver				-400	μΑ
Low lovel output ourrent la	Driver				60	A
ow-level output current, I _{OL} Driver Receiver	·			8	mA	
Operating free-air temperature, T	\ \		0		70	°C

NOTE 2: Differential-input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS	MIN	TYP†	MAX	UNIT	
٧ _{IK}	Input clamp voltage	$I_{I} = -18 \text{ mA}$				-1.5	V	
Vон	High-level output voltage	$V_{IH} = 2 V,$ $I_{OH} = -33 \text{ mA}$	V _{IL} = 0.8 V,		3.7		٧	
VOL	Low-level output voltage	V _{IH} = 2 V, I _{OH} = 33 mA	V _{IL} = 0.8 V,		1.1		V	
VOD1	Differential output voltage	IO = 0			2V _{OD2}	V		
11/22-1	Differential output voltage	$R_L = 100 \Omega$,	See Figure 1	2	2.7		V	
IVOD2I	Differential output voltage	$R_L = 54 \Omega$,	See Figure 1	1.5	2.4		V	
Δ V _{OD}	Change in magnitude of differential output voltage‡				±0.2	V		
Voc	Common-mode output voltage§	R _L = 54 Ω or 100 Ω , See Figure 1				3	V	
∆IVocl	Change in magnitude of common-mode output voltage ‡					±0.2	V	
1-	Outrout coment	Output disabled,	V _O = 12 V			1	A	
Ю	Output current	See Note 3	V _O = -7 V			-0.8	mA	
lн	High-level input current	V _I = 2.4 V				20	μΑ	
I _Ι L	Low-level input current	V _I = 0.4 V				-400	μΑ	
		V _O = -7 V				-250		
los	Short-circuit output current	VO = VCC	250			mA		
		V _O = 12 V				500		
	Complex compact (total montages)	Natard	Outputs enabled		35	50	A	
Icc	Supply current (total package)	No load	Outputs disabled		26	40	mA	

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST C	TEST CONDITIONS			MAX	UNIT
t _d (OD)	Differential-output delay time	$R_1 = 60 \Omega$	See Figure 3		40	60	ns
t _t (OD)	Differential-output transition time	KL = 60 22,	See Figure 3		65	95	ns
^t PZH	Output enable time to high level	$R_L = 110 \Omega$,	See Figure 4		55	90	ns
t _{PZL}	Output enable time to low level	$R_L = 110 \Omega$,	See Figure 5		30	50	ns
tPHZ	Output disable time from high level	$R_L = 110 \Omega$,	See Figure 4		85	130	ns
tPLZ	Output disable time from low level	$R_L = 110 \Omega$,	See Figure 5		20	40	ns

[†] All typical values are at V_{CC} = 5 V and T_A = 25°C. ‡ $\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC} respectively, that occur when the input is changed from a high level to a low

[§] In ANSI Standard EIA/TIA-422-B, VOC, which is the average of the two output voltages with respect to GND, is called output offset voltage, VOS. NOTE 3: This applies for both power on and off; refer to ANSI Standard EIA/TIA-422-B for exact conditions.

RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST COI	NDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	$V_0 = 2.7 V$,	$I_0 = -0.4 \text{ mA}$			0.2	V
V _{IT} _	Negative-going input threshold voltage	$V_0 = 0.5 V$,	IO = 8 mA	-0.2‡			V
V _{hys}	Input hysteresis voltage (V _{IT+} - V _{IT-})				50		mV
٧ıĸ	Enable clamp voltage	$I_{I} = -18 \text{ mA}$				-1.5	V
Vон	High-level output voltage	V _{ID} = 200 mV, See Figure 2	$I_{OH} = -400 \mu A$,	2.7			٧
VOL	Low-level output voltage	$V_{ID} = -200 \text{ mV},$ See Figure 2	$I_{OL} = 8 \text{ mA},$			0.45	٧
loz	High-impedance-state output current	$V_0 = 0.4 \text{ V to } 2.4 \text{ V}$	J			±20	μΑ
١.	Line input current	Other input = 0 V,	V _I = 12 V			1	A
11	Line input current	See Note 3	V _I = -7 V			-0.8	mA
ΙΗ	High-level enable input current	V _{IH} = 2.7 V				20	μΑ
I _I L	Low-level enable input current	V _{IL} = 0.4 V				-100	μΑ
rį	Input resistance			12			kΩ
IOS	Short-circuit output current			-15		-85	mA
loo	Supply current (total package)	No load	Outputs enabled		35	50	mA
Icc	Зарріў сапені (юtаі раскаўе)	I No load	Outputs disabled		26	40	IIIA

switching characteristics, V_{CC} = 5 V, C_L = 15 pF, T_A = 25°C

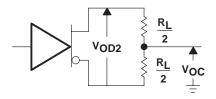
	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Propagation delay time, low-to-high-level output	V _{ID} = −1.5 V to 1.5 V, See Figure 6		21	35	ns
^t PHL	Propagation delay time, high-to-low-level output	V _{ID} = -1.5 V to 1.5 V, See Figure 0		23	35	ns
^t PZH	Output enable time to high level	See Figure 7		10	30	ns
tPZL	Output enable time to low level	See Figure 7		12	30	ns
tPHZ	Output disable time from high level	See Figure 7		20	35	ns
t _{PLZ}	Output disable time from low level	See Figure 7		17	25	ns



[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

NOTE 3: This applies for both power on and power off. Refer to ANSI Standard EIA/TIA-422-B for exact conditions.

PARAMETER MEASUREMENT INFORMATION



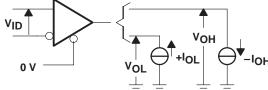
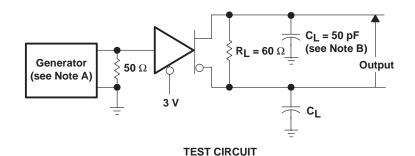
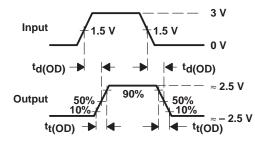


Figure 1. Driver VOD and VOC

Figure 2. Receiver VOH and VOL

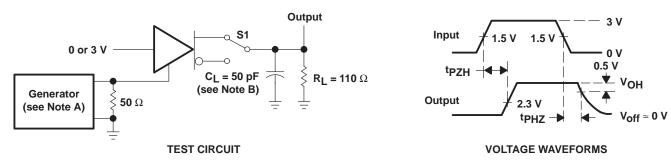




VOLTAGE WAVEFORMS

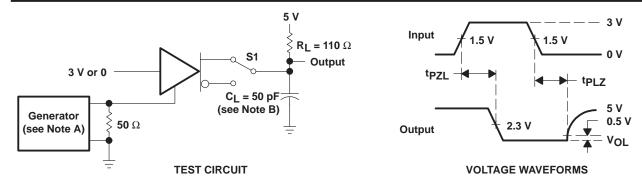
- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, 50% duty cycle, $t_f \le 6$ ns, $t_f \le 6$ ns, $Z_O = 50 \Omega$.
 - B. CL includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Voltage Waveforms



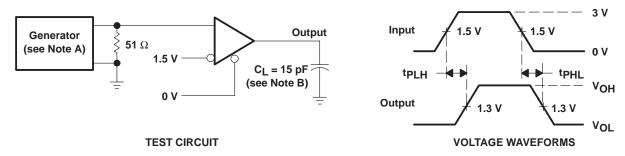
- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, 50% duty cycle, $t_f \le 6$ ns, $t_f \le 6$ ns,
 - B. C_L includes probe and jig capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, 50% duty cycle, $t_{\Gamma} \le 6$ ns, t_{Γ
 - B. C_L includes probe and jig capacitance.

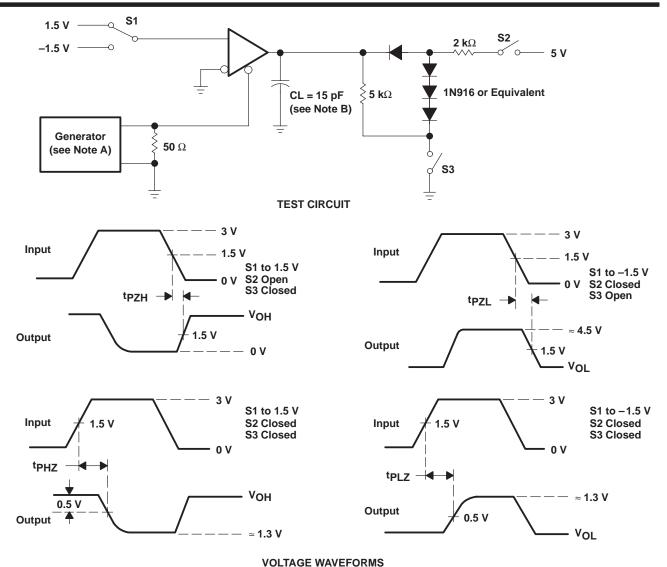
Figure 5. Driver Test Circuit and Voltage Waveforms



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, 50% duty cycle, $t_{\Gamma} \le 6$ ns, t_{Γ
 - B. C_L includes probe and jig capacitance.

Figure 6. Receiver Test Circuit and Voltage Waveforms



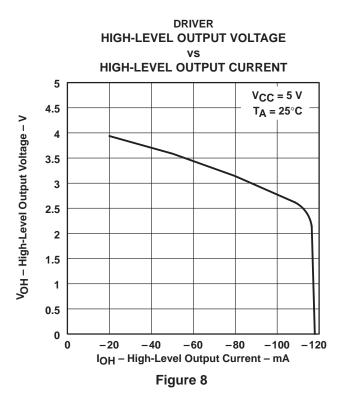


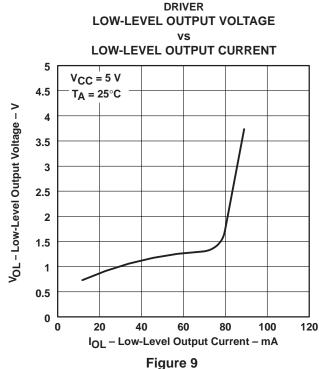
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, 50% duty cycle, $t_{\Gamma} \le 6$ ns, $t_{f} \le 6$ ns, t_{f

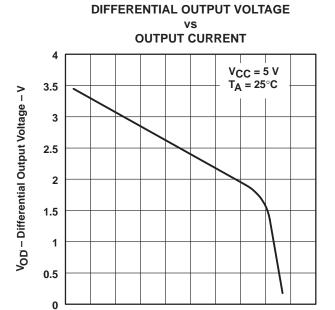
B. CL includes probe and jig capacitance.

Figure 7. Receiver Test Circuit and Voltage Waveforms

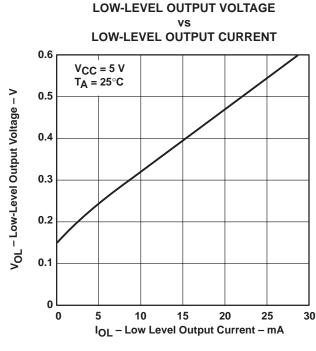
TYPICAL CHARACTERISTICS







DRIVER



RECEIVER

Figure 10

50

IO - Output Current - mA

60

40

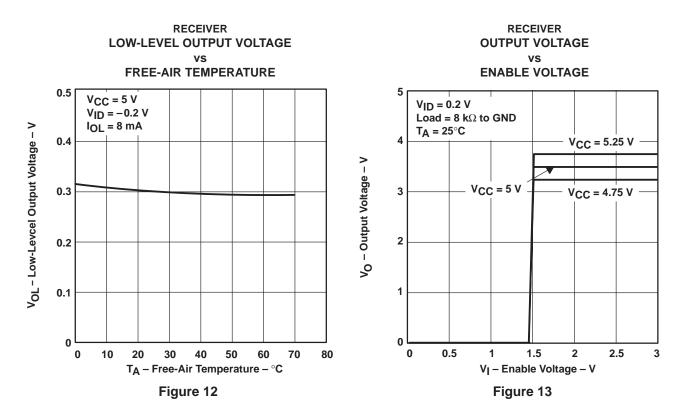
10 20

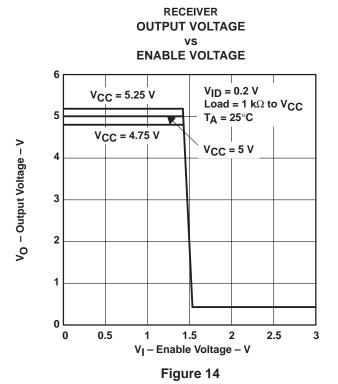
70

80 90 100

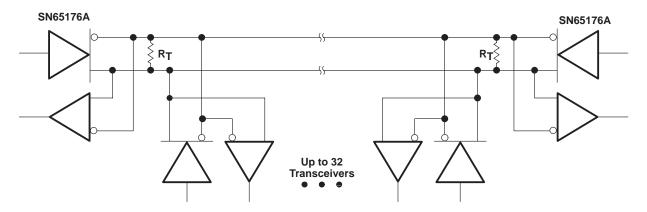
Figure 11

TYPICAL CHARACTERISTICS





APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance (R_T = Z_O). Stub lengths off the main line should be kept as short as possible.

Figure 15. Typical Application Circuit







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75176AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176ADE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176ADG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176ADRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176AP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75176APE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

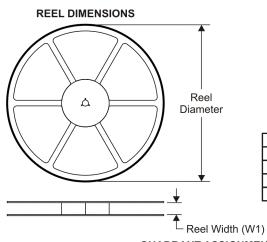
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75176ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1





*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	SN75176ADR	SOIC	D	8	2500	340.5	338.1	20.6

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



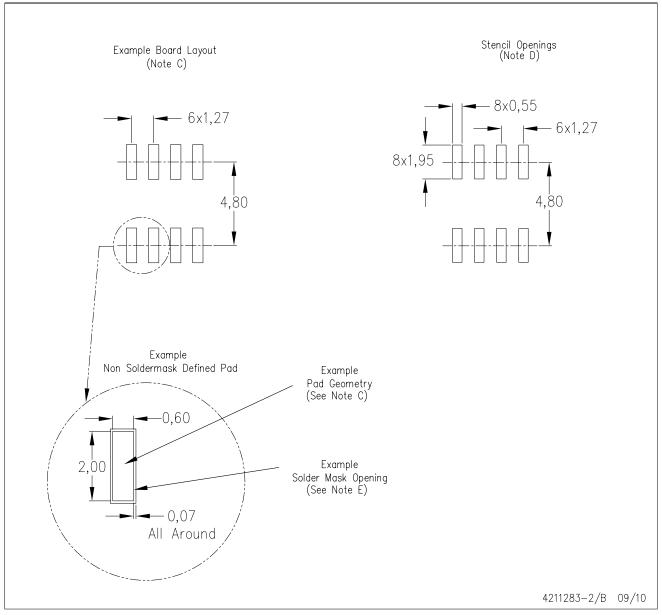
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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